when executed by a processor, cause the processor to control a semiconductor
wafer processing system to perform the steps of:

supplying a cleaning agent to a chamber after a substrate is removed
therefrom;

pumping said cleaning agent from the chamber through a pumping system
having a turbomolecular pump and roughing pump coupled in parallel;

at least partially opening a valve coupled between said chamber and the
turbomolecular pump of the pumping system; and

drawing at least a portion of said cleaning agent through said
turbomolecular pump.

B)   Please add the following new claims:

–16. (New) The computer-readable medium of claim 6 further comprising:

drawing a portion of said cleaning agent through the roughing pump.

17.   (New) The computer-readable medium of claim 6, wherein the step of at
least partially opening the valve coupled between the chamber and the
turbomolecular pump further comprises:

partially opening the valve.

18.   (New) A computer-readable medium having stored thereon a plurality of
instructions, the plurality of instructions including instructions which, when
executed by a processor, cause the processor to control a semiconductor wafer
processing system to perform the steps of:

supplying a cleaning agent to a deposition chamber;

pumping said cleaning agent from the deposition chamber through a
pumping system having a turbomolecular pump and roughing pump coupled in
parallel;

partially opening a valve coupled between said deposition chamber and
the turbomolecular pump of the pumping system; and